

What is claimed is:

1. A failure analyzing device which displays failure distributions before and after a wafer is divided into a plurality of semiconductor memory chips in association with positions on said wafer.
2. A failure analyzing device comprising:
 - a chip position analyzing device which estimates a position of chip on a wafer;
 - a failure distribution mapping device which maps a distribution of semiconductor chips which have become faulty; and
 - a failure cause determining device which determines a cause of a failure from said distribution.
3. A failure analyzing device according to claim 2, wherein said chip position analyzing device estimates said position on said wafer based on a replacement address of a semiconductor memory.